

Date Created : 2007/12/03
Date Issued On : 2008/01/22
PCN# : Q4074901

DESIGN/PROCESS CHANGE NOTIFICATION -- FINAL

This is to inform you that a design and/or process change will be made to the following product(s). This notification is for your information and concurrence.

If you require data or samples to qualify this change, please contact **Fairchild Semiconductor within 30 days of receipt of this notification.**

Updated process quality documentation, such as FMEAs and Control Plans, are available for viewing upon request.

If you have any questions concerning this change, please contact:

Technical Contact:

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PCN Originator:

Name: SONG, HEEYUNG
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Phone: 82-32-680-1216

Implementation of change:

Expected 1st Device Shipment Date: 2008/04/06

Earliest Year/Work Week of Changed Product: 0815

Change Type Description: Test Location

Description of Change (From): Assembly & TEST: Fine Silicon Power Networks(FineSPN)

Description of Change (To): Assembly: Fine Silicon Power Networks(FineSPN) Test: DB Power Tech Inc. It's also certified for ISO9001 and ISO14001 certificated.

Reason for Change : Outsourcing of Final test. There are no changes to equipment and system.

Qual/REL Plan Numbers : Q20070533

Qualification :

This change doesn't require Reliability test.

Results/Discussion

Test: (Bake)			
Lot	Device	24-HOURS	Failure Code
Q20070533AABAKE	FMG2G75US60	0/11	

Product Id Description : All IGBT MODULE devices packaged with 25PM-AA, 7PM-GA, 7PM-HA, 7PM-IA. The products affected by this change are listed below in the "Affected FSIDs" section.

Affected FSIDs :

FMG2G100US60	FMG2G150US60	FMG2G150US60E
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FMG2G200US60	FMG2G300LS60E	FMG2G300US60
FMG2G300US60E	FMG2G400LS60	FMG2G400US60
FMG2G50US60	FMG2G75US60	